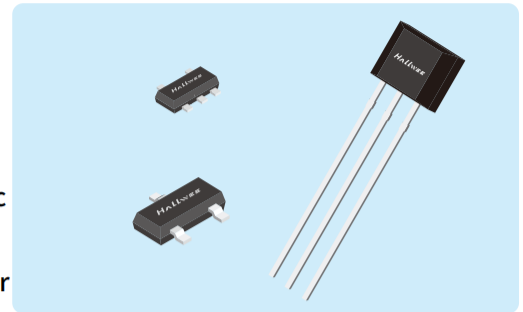


1. General Description

The HAL251 is fabricated from mixed signal CMOS technology. It internally includes an on-chip Hall voltage generator, a voltage regulator for operation with supply voltages of 1.8 to 5.5V, a sleep/awake logic for low power consumption, temperature compensation circuitry, small-signal amplifier, Hall sensor with dynamic offset cancellation system, Schmitt trigger and an open-drain output. Both south pole and north pole of sufficient strength will turn the sensor output on. The output will be turned off under no magnetic field. While the magnetic flux density (B) is larger than operating point (Bop), the output will be turned on (low), the output is held until B is lower than release point (Brp), and then turned off.



The total power consumption in normal operation is typically 15 μ W with a 3.3V power source. Operating temperature range of the HAL251 is from -40°C to 85°C.

2. Features and Benefits

CMOS Hall IC Technology

Strong RF noise protection

1.6 to 5.5V for battery-powered applications

Micropower consumption

Multi Small Size option

Low sensitivity drift in crossing of Temp. range Ultra Low power consumption at 5 μ A (Avg)

High ESD Protection, HBM > +/- 4KV (min) Totem-pole output

Package: TO-92S, SOT23-3, SOT553, DFN1216-4L

3. Applications

Solid state switch

Handheld Wireless Handset Awake Switch (Flip Cell/PHS Phone/Note Book/Flip Video Set)

Magnet proximity sensor for reed switch replacement in low duty cycle applications

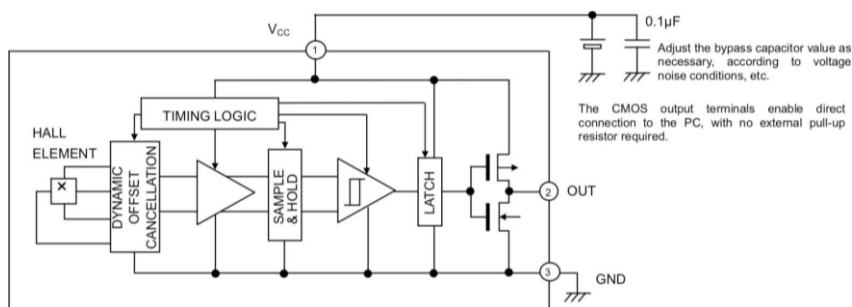
Notebook / PAD PC / PDA

4. Typical Application Circuit

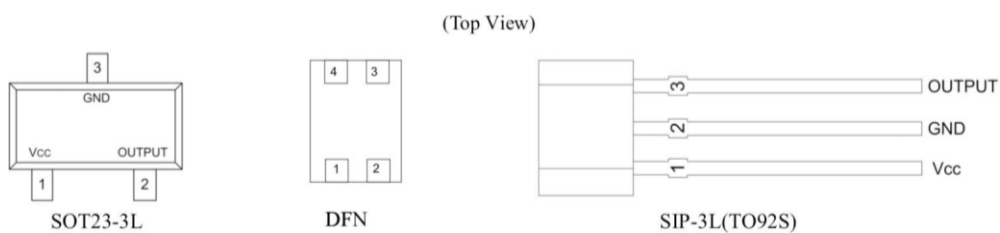
Our pole-independent sensing technique allows for operation with either a north pole or south pole magnet orientation, enhancing the manufacturability of the device. The state-of-the-art technology provides the same output polarity for either pole face.

It is strongly recommended that an external bypass capacitor be connected (in close proximity to the Hall sensor) between the supply and ground of the device to reduce both external noise and noise generated by the chopper-stabilization technique. This is especially true due to the relatively high impedance of battery supplies.

5. Functional Block Diagram



6. Pinning



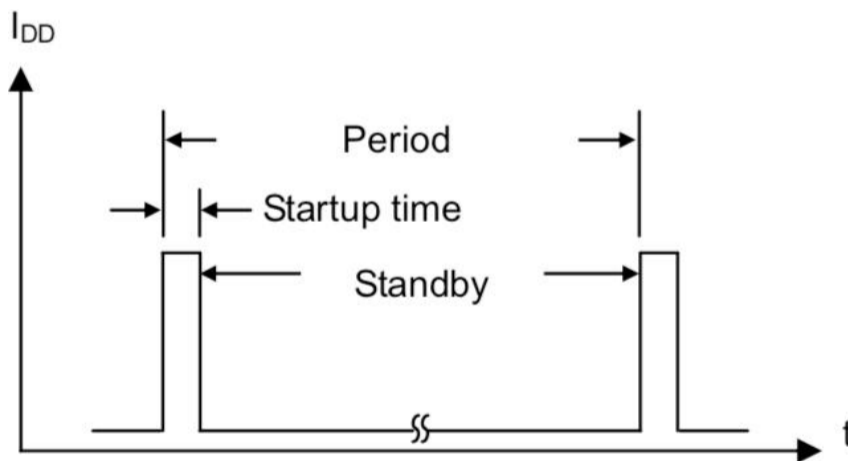
| SOT Pin Number | SIP Pin Number | Pin Name | Function |
|----------------|----------------|----------|----------------|
| 1 | 1 | VCC | Supply Voltage |
| 2 | 3 | OUT | CMOS Output |
| 3 | 2 | GND | Ground |
| 4 | NC | | |

SOT553



| Pin Name | Pin No. SOT553 | I/O | Pin Function |
|----------|-------------------|-----|--------------------|
| VCC | 4 | P | Input Power Supply |
| GND | 2 | P | Ground |
| NC | 1, 3 | - | Not Connected |
| OUT | 5 | O | Output Pin |

7. DESCRIPTION of OPERATIONS

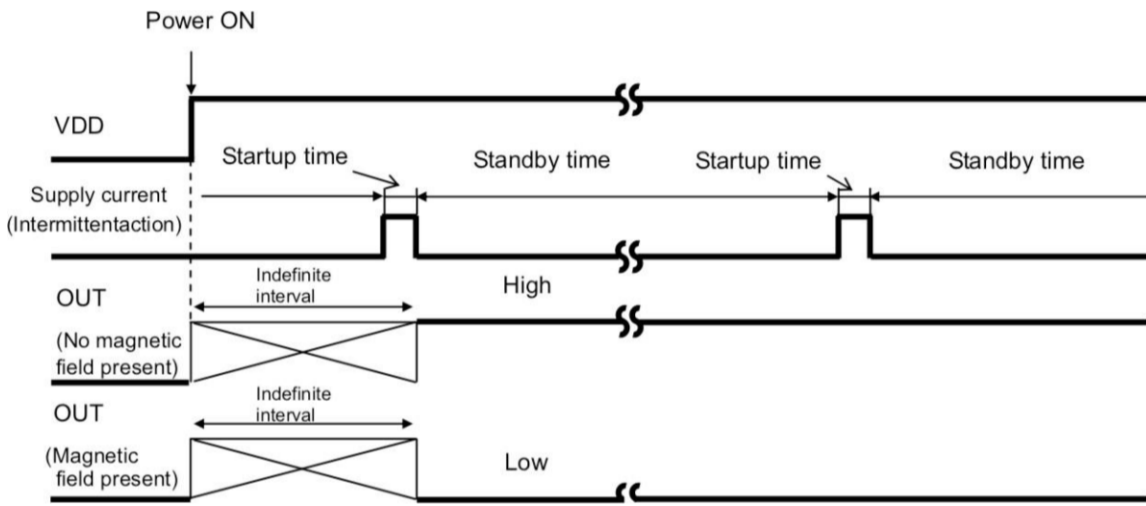


The unipolar detection Hall IC adopts an intermittent operation method to save energy. At startup, the Hall elements, amp, comparator and other detection circuit power ON and magnetic detection begins. During standby, the detection circuits power OFF, thereby reducing current consumption. The detection results are held while standby is active, and then output.

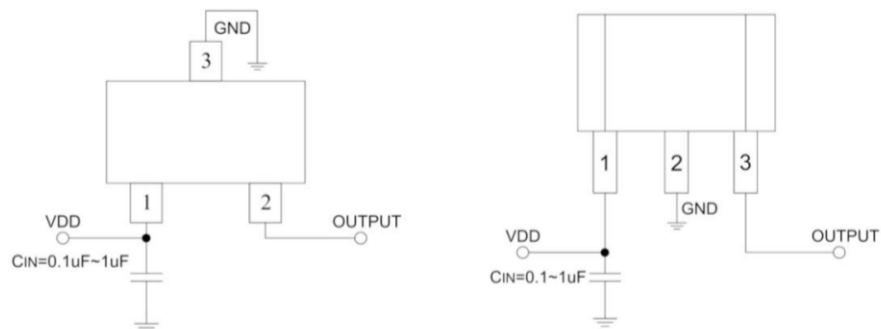
Reference period: 50ms (MAX100ms) Reference startup time: 24 μ s

INTERMITTENT OPERATION at POWER ON

The unipolar detection Hall IC adopts an intermittent operation method in detecting the magnetic field during startup, as shown in Fig.5. It outputs to the appropriate terminal based on the detection result and maintains the output condition during the standby period. The time from power ON until the end of the initial startup period is an indefinite interval, but it cannot exceed the maximum period, 100ms. To accommodate the system design, the Hall IC output read should be programmed within 100ms of power ON, but after the time allowed for the period ambient temperature and supply voltage.



8. Typical Application Circuit



Note: C_{IN} is for power stabilization and to strengthen the noise immunity, the recommended capacitance is 0.1~1uF.

9. Absolute Maximum Ratings

| Parameter | Symbol | Value | Units |
|-----------------------------|-----------|------------|-------|
| Supply Voltage(operating) | V_{DD} | 6 | V |
| Supply Current | I_{DD} | 1 | mA |
| Output Voltage | V_{OUT} | 6 | V |
| Output Curent | I_{OUT} | 1 | mA |
| Operating Temperature Range | T_A | -40 to 85 | °C |
| Storage Temperature Rang | T_S | -50 to 150 | °C |
| ESD Sensitivity | - | 4000 | V |

Exceeding the absolute maximum ratings may cause permanent damage. Exposure to absolute-maximum rated conditions for extended periods may affect device reliability.

10. Magnetic Characteristics

Operating Parameters: $T_A = 25^\circ\text{C}$, $V_{DD}=2.75V_{DC}$.

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Units |
|---|----------------|---|------|------|------|-------|
| $B_{OP\ S}$ | Operated point | $T_A=25^\circ\text{C}$ | 20 | 35 | 50 | Gs |
| | | $T_A=-40^\circ\text{C to }85^\circ\text{C}$ | - | 37 | - | |
| $T_A=25^\circ\text{C}$ | | -20 | -35 | -50 | | |
| $T_A=-40^\circ\text{C to }85^\circ\text{C}$ | | - | -37 | - | | |
| $B_{RP\ S}$ | Release point | $T_A=25^\circ\text{C}$ | 8 | 23 | 40 | |
| | | $T_A=-40^\circ\text{C to }85^\circ\text{C}$ | - | 25 | - | |
| $T_A=25^\circ\text{C}$ | | -8 | -23 | -40 | | |
| $T_A=-40^\circ\text{C to }85^\circ\text{C}$ | | - | -25 | - | | |
| $B_{HY\ S}$ | Hysteresis | $T_A=25^\circ\text{C}$ | - | 12 | - | |
| | | $T_A=-40^\circ\text{C to }85^\circ\text{C}$ | - | 12 | - | |

10. DC Electrical Characteristics

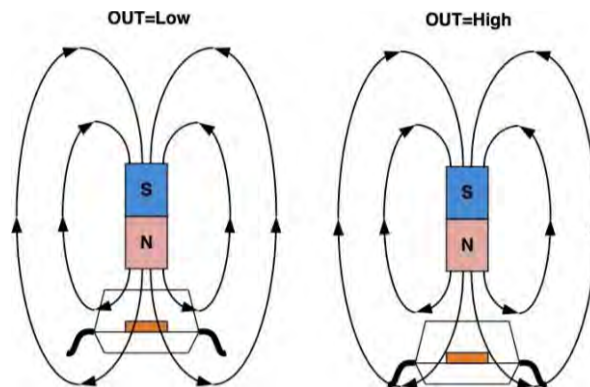
 DC Operating Parameters: $T_A = 25^\circ\text{C}$, $V_{DD}=2.75\text{V}$.

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Units |
|--------------------------------------|----------------|---|--------------|------|-----|---------------|
| Operating voltage | V_{DD} | Operating | 1.6 | 3.3 | 5.5 | V |
| Output High Voltage | V_{OH} | $B < BrpS$ $I_{OUT} = -0.5\text{mA}$ | $V_{DD}-0.2$ | - | - | |
| Output Low Voltage | V_{OL} | $BopS < B$ $I_{OUT} = +0.5\text{mA}$ | - | - | 0.2 | |
| Supply current1 | $I_{DDI(AVG)}$ | $V_{DD}=1.8\text{V}$, Average | - | 1.1 | - | μA |
| Supply Current During Startup Time 1 | $I_{DDI(EN)}$ | $V_{DD}=1.8\text{V}$, During StartupTime Value | - | 0.7 | - | mA |
| Supply Current During Standby Time 1 | $I_{DDI(DIS)}$ | $V_{DD}=1.8\text{V}$, During StandbyTime Value | - | 0.42 | - | μA |
| Supply current1 | $I_{DDI(AVG)}$ | $V_{DD}=3.0\text{V}$, Average | - | 2.4 | - | μA |
| Supply Current During Startup Time 1 | $I_{DDI(EN)}$ | $V_{DD}=3.0\text{V}$, During StartupTime Value | - | 1 | - | mA |
| Supply Current During Standby Time 1 | $I_{DDI(DIS)}$ | $V_{DD}=3.0\text{V}$, During StandbyTime Value | - | 1.4 | - | μA |
| Awake mode time | T_{AW} | Operating | - | 25 | - | μS |
| Sleep mode time | T_{SL} | Operating | - | 50 | 100 | mS |

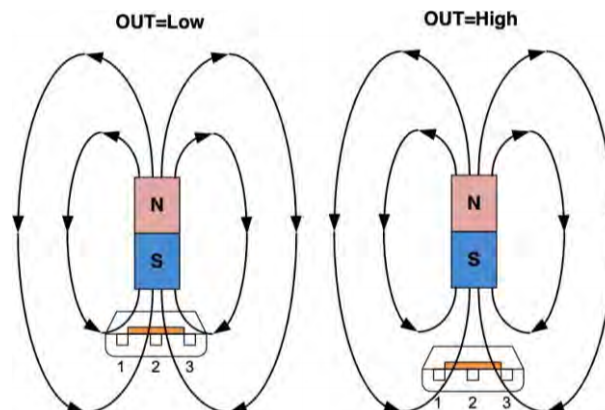
12. Field Direction Definition

A positive magnetic field is defined as a south pole near the marked side of the package.

TO-92S /SOT553 package



DFN1616 /SOT23-3 package



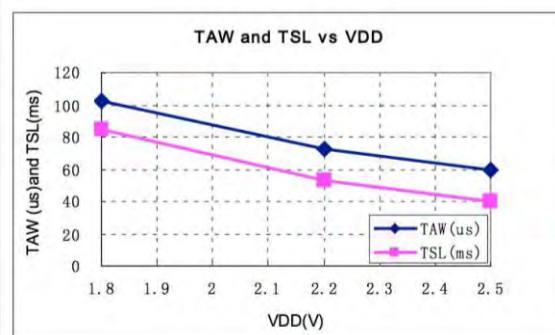
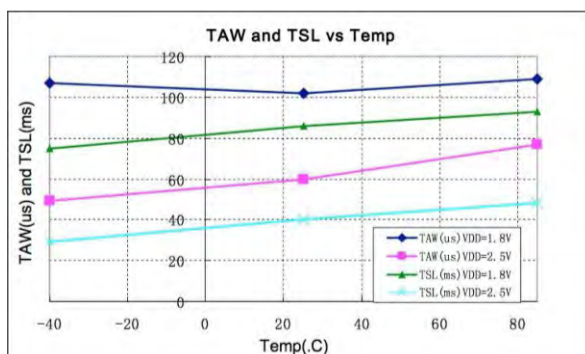
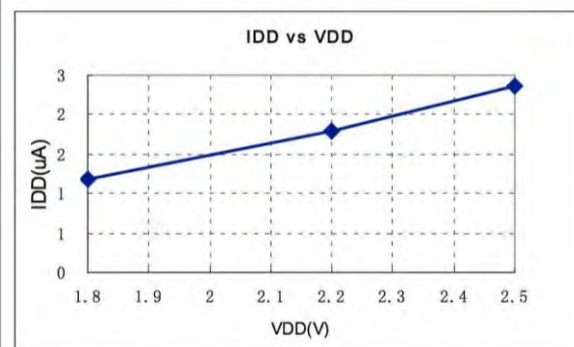
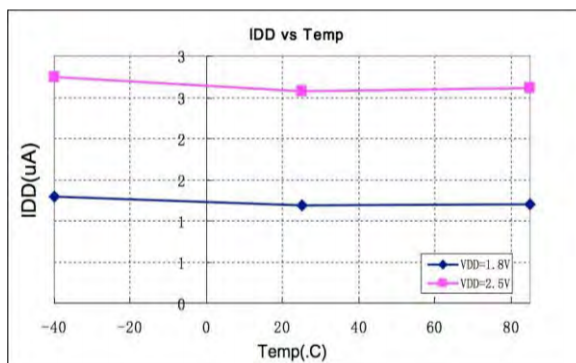
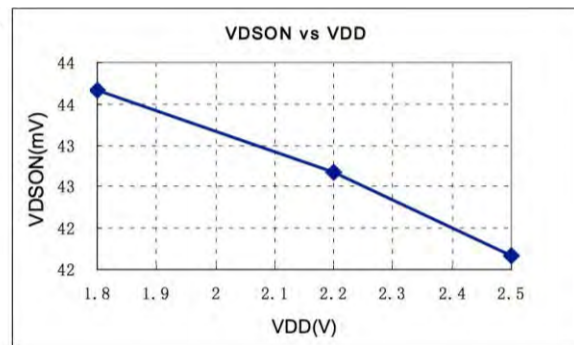
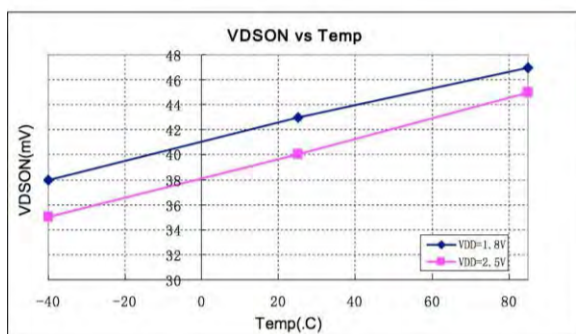
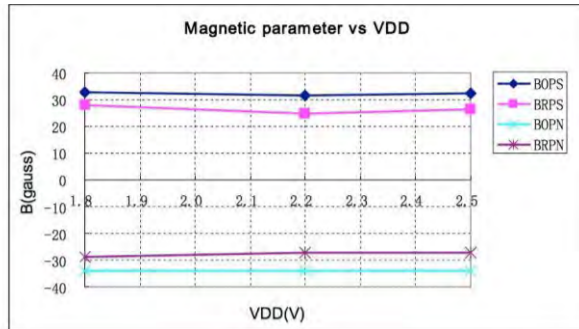
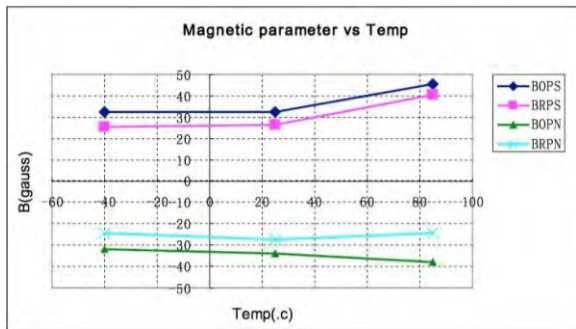
If the device is powered on with a magnetic field strength between B_{RP} and B_{OP} , then the device output is determinate High. For UA package, if the field strength is greater than B_{OP} , then the output is pulled low. If the field strength is less than B_{RP} , the output is released. For SO package, however, if the field strength is less than B_{OP} , then the output is pulled low. If the field strength is greater than B_{RP} , the output is released.

13. ESD Protection

Human Body Model (HBM) tests according to: Mil. Std. 883F method 3015.7

| Parameter | Symbol | Limit Values | | Unit | Notes |
|-------------|-----------|--------------|---------|------|-------|
| | | Min | Max | | |
| ESD Voltage | V_{ESD} | | ± 4 | kV | |

14. Performance Characteristics



15. Unique Features

CMOS Hall IC Technology

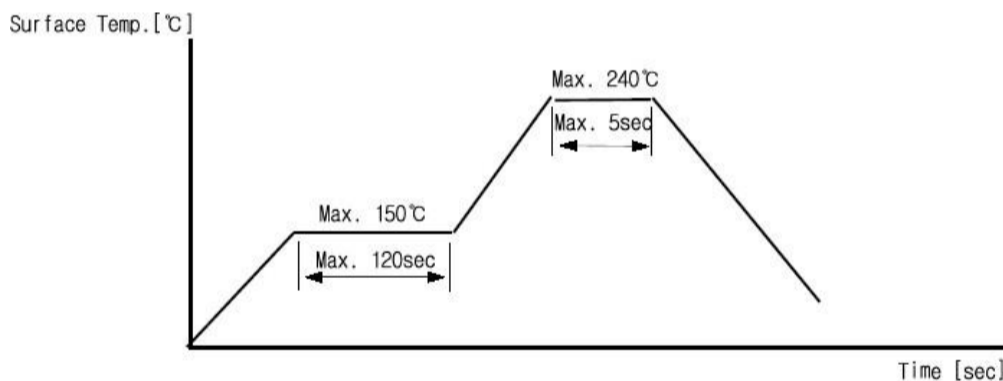
The chopper stabilized amplifier uses switched capacitor techniques to eliminate the amplifier offset voltage, which, in bipolar devices, is a major source of temperature sensitive drift. CMOS makes this advanced technique possible. The CMOS chip is also much smaller than a bipolar chip, allowing very sophisticated circuitry to be placed in less space. The small chip size also contributes to lower physical stress and less power consumption.

Installation Comments

Consider temperature coefficients of Hall IC and magnetics , as well as air gap and life time variations.

Observe temperature limits during wave soldering. Typical IR solder-reflow profile:

- No Rapid Heating and Cooling.
- Recommended Preheating for max. 2minutes at 150°C
- Recommended Reflowing for max. 5seconds at 240°C

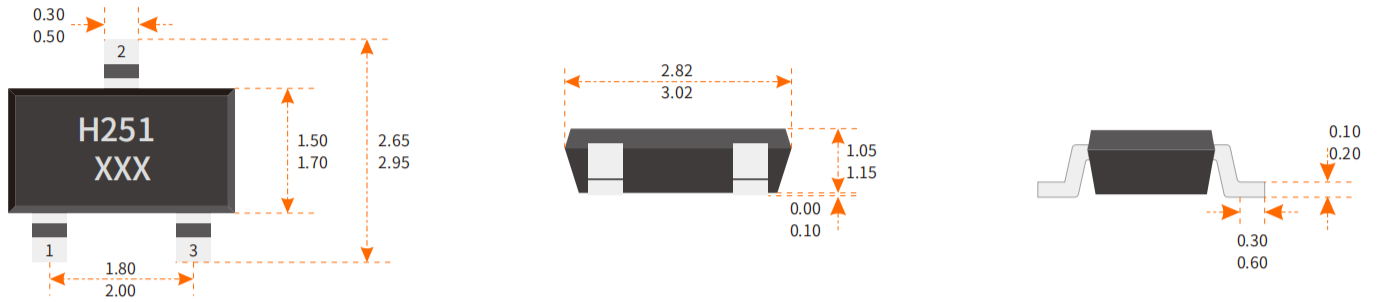


16. ESD Precautions

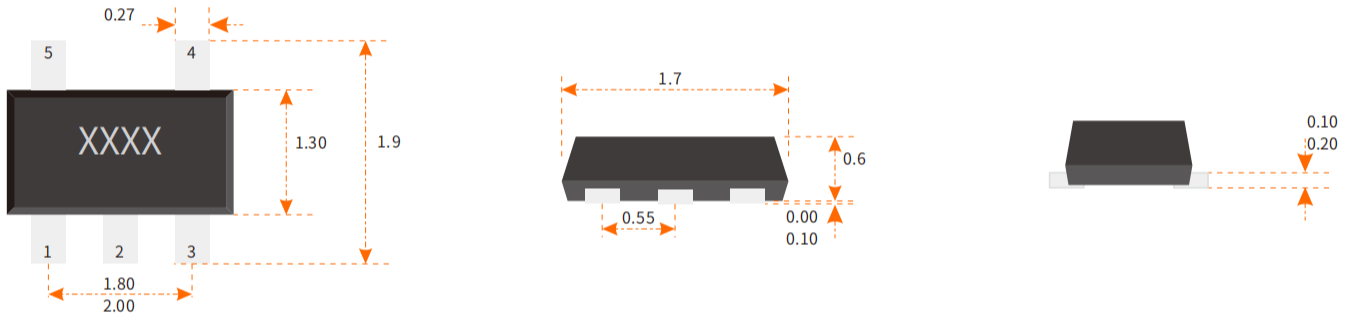
Electronic semiconductor products are sensitive to Electro Static Discharge (ESD). Always observe Electro Static Discharge control procedures whenever handling semiconductor products.

17. Package Information

SOT-23SO



SOT-553SO



TO-92SUA

